

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package Name	Standard Dimensions mm (inch)
1	IC7, IC11, IC22, IC29, IC53, IC65	6		TC7SZ04AFS	TOSHIBA			
2	IC14, IC18	2		S1213B00HV5T2	ABLIC	LDO, 500mA		
3	IC15, IC19	2		TLV709A01DBVR	Texas Instruments	LDO, 150mA		
4	IC17, IC21	2		TCR1HF50B	TOSHIBA			
5	IC23, IC25, IC26, IC28, IC31, IC32, IC36, IC37, IC40, IC41, IC42, IC44, IC45, IC48, IC54, IC56, IC57, IC60	18		TC7PZ14FU	TOSHIBA			
6	IC24, IC30	2		TC75S57FU	TOSHIBA			
7	IC27, IC33, IC43, IC49, IC55, IC61	6		TC7WZ00FK	TOSHIBA			
8	IC34, IC38, IC46, IC47, IC58, IC59	6		TC7WZ08FK	TOSHIBA			
9	IC35, IC39	2		UCC27301ADRCR	Texas Instruments	Half bridge gate driver		
10	IC50, IC62	2		LTC1440IMS8	Analog Devices	Comparator		
11	IC51, IC64	2		LM393BIDDFR	Texas Instruments	Comparator		
12	Q7, Q10, Q11, Q14, Q22, Q23, Q28, Q29	8		2SC5658T2LR	ROHM	NPN, 50V, 150mA		
13	Q8, Q12, Q24, Q25, Q30, Q31	6		SSM3K15AFS	TOSHIBA			
14	Q9, Q13	2		SSM3K318R	TOSHIBA			
15	Q15, Q16, Q17, Q18, Q19, Q20	6		SSM6K804R	TOSHIBA			
16	Q21, Q27	2		HN4A56JU	TOSHIBA			
17	D24, D25, D42, D43	4		CEZ5V6	TOSHIBA			
18	D26, D27, D28, D29, D34, D35, D36, D37	8		CRF03A	TOSHIBA			
19	R27, R48	2	200kΩ			100mW, ±1%		1.6 x 0.8 (0603)
20	R28, R49	2	2kΩ			100mW, ±1%		1.6 x 0.8 (0603)
21	R30, R34, R51, R55	4	1MΩ			100mW, ±1%		1.6 x 0.8 (0603)
22	R31, R52	2	4.7MΩ			100mW, ±1%		1.6 x 0.8 (0603)
23	R33, R54	2	20kΩ			100mW, ±1%		1.6 x 0.8 (0603)
24	R35, R56	2	3.3MΩ			100mW, ±1%		1.6 x 0.8 (0603)
25	R65, R73, R74, R75, R83, R84, R89, R109	8	10kΩ			100mW, ±5%		1.6 x 0.8 (0603)
26	R66, R69, R71, R76, R79, R81	6	5.1kΩ			100mW, ±5%		1.6 x 0.8 (0603)
27	R67, R70, R77, R80	4	47kΩ			100mW, ±5%		1.6 x 0.8 (0603)

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28	R68, R78	2	470Ω			100mW, ±5%		1.6 x 0.8 (0603)
29	R72, R82, R94, R95, R100, R101, R114, R115, R120, R121	10	10Ω			100mW, ±5%		1.6 x 0.8 (0603)
30	R85, R105	2	220Ω			100mW, ±1%		1.6 x 0.8 (0603)
31	R86, R106	2	1.1kΩ			100mW, ±1%		1.6 x 0.8 (0603)
32	R88, R91, R92, R108, R111, R112	6	4.7Ω			1W, ±1%		3.2 x 5.0 (1220)
33	R90, R103, R110, R123, R177, R182	6	0Ω					1.6 x 0.8 (0603)
34	R93, R97, R99, R113, R117, R118	6	11Ω			1W, ±1%		3.2 x 5.0 (1220)
35	R98, R119	2	500Ω			100mW, ±5%		1.6 x 0.8 (0603)
36	R104, R124	2	20Ω			100mW, ±1%		1.6 x 0.8 (0603)
37	R125, R150	2	43kΩ			100mW, ±1%		1.6 x 0.8 (0603)
38	R126, R128, R137, R139, R151, R152, R162, R164	8	30kΩ			100mW, ±5%		1.6 x 0.8 (0603)
39	R127, R153, R187, R188	4	100kΩ			100mW, ±1%		1.6 x 0.8 (0603)
40	R129, R154	2	8.2kΩ			100mW, ±1%		1.6 x 0.8 (0603)
41	R130, R155	2	2.2kΩ			100mW, ±1%		1.6 x 0.8 (0603)
42	R131, R156	2	1kΩ			100mW, ±1%		1.6 x 0.8 (0603)
43	R132, R157	2	12kΩ			100mW, ±1%		1.6 x 0.8 (0603)
44	R133, R158	2	10kΩ			100mW, ±1%		1.6 x 0.8 (0603)
45	R134, R140, R159, R165	4	27kΩ			100mW, ±1%		1.6 x 0.8 (0603)
46	R135, R160	2	3.3kΩ			100mW, ±1%		1.6 x 0.8 (0603)
47	R136, R138, R143, R161, R163, R168, R178, R179, R183, R184	10	1kΩ			100mW, ±5%		1.6 x 0.8 (0603)
48	R142, R167	2	3kΩ			100mW, ±1%		1.6 x 0.8 (0603)
49	R144, R169	2	4.7kΩ			100mW, ±5%		1.6 x 0.8 (0603)
50	R146, R171	2	15kΩ			100mW, ±1%		1.6 x 0.8 (0603)
51	R147, R172	2	18kΩ			100mW, ±1%		1.6 x 0.8 (0603)
52	R149, R173	2	2.4MΩ			100mW, ±1%		1.6 x 0.8 (0603)
53	R175, R176, R180, R181	4	220Ω			100mW, ±5%		1.6 x 0.8 (0603)

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package Name	Standard Dimensions mm (inch)
54	C24, C28, C69, C70, C72, C73, C74, C76, C79, C80, C82, C83, C84, C85, C93, C94, C96, C100, C105, C106, C108, C112, C113, C114, C115, C117, C118, C119, C122, C123, C126, C127, C133, C134, C136, C137, C138, C139, C142, C143, C146, C148	42	0.1μF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
55	C35, C40, C54, C59, C71, C81, C124, C144	8	1μF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
56	C37, C56, C95, C107	4	4.7μF			Ceramic, 50V, ±10%		2.0 x 1.25 (0805)
57	C39, C47, C48, C57, C66, C67	6	0.47μF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
58	C75, C77, C78, C86, C87, C88	6	68pF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
59	C89, C101	2	120pF			Ceramic, 100V, ±10%		1.6 x 0.8 (0603)
60	C90, C97, C102, C109, C153, C154, C156, C157	8	10μF			Ceramic, 50V, ±20%		2.0 x 1.25 (0805)
61	C99, C111	2	20pF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
62	C116, C120, C121, C131, C135, C140, C141, C151	8	10nF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
63	C128, C149	2	10pF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
64	C129, C132, C147, C152	4	1nF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
65	C155, C158	2	1000pF			Ceramic, 50V, ±10%		1.6 x 0.8 (0603)
66	CN2, CN3	2		PMW-61-5PW	MAC8	Connector		
67	P2, P3, P4, P5, P7, P8	6	TH	TH				

Not Mounted Items

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package Name	Standard Dimensions mm (inch)	Not Mounted
68	D30, D38	2		CRZ10	TOSHIBA				Not Mount
69	D31, D39	2		CUS05F30	TOSHIBA				Not Mount
70	D32, D33, D40, D41	4		CRS04	TOSHIBA				Not Mount
71	R87, R96, R102, R107, R116, R122	6						1.6 x 0.8 (0603)	Not Mount
72	C38, C58, C159, C160	4				Ceramic		2.0 x 1.25 (0805)	Not Mount
73	C91, C92, C98, C103, C104, C110	6				Ceramic		1.6 x 0.8 (0603)	Not Mount

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